Supplier Name:	Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info:	ti.com/support
Form/Declaration Type:	Distribute - RoHS and IEC 62474 DB
Created on:	06/11/2022

### Details for "TPS62040DGQG4"

#### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TPS62040DGQG4	NIPDAUAG	Level-1-260C-UNLIM	Ext-Mfg	DGQ   10	3x3x1	29.2

#### \*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

## **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

## **Component Information**

			Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.052052	99.986554	999866	0.178405	1784
Not Categorized	Proprietary Materials		0.000006	0.011525	115	0.000021	0
Precious Metals	Silver	7440-22-4	0.000001	0.001921	19	0.00003	0
Sub-Total			0.052059	100	1000000	0.178429	1784
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.336072	81.99998	820000	1.151864	11519
Thermoplastics	Ероху	85954-11-6	0.073772	18.00002	180000	0.252849	2528
Sub-Total			0.409844	100	1000000	1.404713	14047
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	13.04076	99.7	997000	44.696329	446963
Magnesium and Its Alloys	Magnesium	7439-95-4	0.00654	0.05	500	0.022415	224
Other Inorganic Materials	Silicon	7440-21-3	0.0327	0.25	2500	0.112077	1121
Sub-Total			13.08	100	1000000	44.830821	448308
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.3892	97.3	973000	1.333957	13340
Precious Metals	Gold	7440-57-5	0.0012	0.3	3000	0.004113	41
Precious Metals	Palladium	7440-05-3	0.0084	2.1	21000	0.02879	288
Precious Metals	Silver	7440-22-4	0.0012	0.3	3000	0.004113	41
Sub-Total			0.4	100	1000000	1.370973	13710
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	12.844066	93.5	935000	44.022173	440222
Other Plastics and Rubber	Carbon Black	1333-86-4	0.068685	0.500001	5000	0.235413	2354
Thermoplastics	Ероху	85954-11-6	0.824218	5.999999	60000	2.824952	28250
Sub-Total			13.736969	100	1000000	47.082538	470825
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	1.497484	100	1000000	5.132526	51325
Sub-Total			1.497484	100	1000000	5.132526	51325
Total			29.176356			100	1000000

#### Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component. The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

See Glossary of Terms for more details.

## **Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

## Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

# Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

## Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 06/11/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.